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FIG. 3B shows a cross-sectional view along a y-axis of a semiconductor substrate illustrating a step of a first embodiment of a semiconductor device fabrication method;

FIG. 4A shows a cross-sectional view along an x-axis of a semiconductor substrate illustrating a subsequent step of a first embodiment of a semiconductor device fabrication method;

FIG. 4B shows a cross-sectional view along a y-axis of a semiconductor substrate illustrating a subsequent step of a first embodiment of a semiconductor device fabrication method;

FIG. 5A shows a cross-sectional view along an x-axis of a semiconductor substrate illustrating a subsequent step of a first embodiment of a semiconductor device fabrication method;

FIG. 5B shows a cross-sectional view along a y-axis of a semiconductor substrate illustrating a subsequent step of a first embodiment of a semiconductor device fabrication method;

FIG. 6A shows a cross-sectional view along an x-axis of a semiconductor substrate illustrating a subsequent step of a first embodiment of a semiconductor device fabrication method;

FIG. 6B shows a cross-sectional view along a y-axis of a semiconductor substrate illustrating a subsequent step of a first embodiment of a semiconductor device fabrication method;

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FIG. 7A shows a cross-sectional view along an x-axis of a semiconductor substrate illustrating a subsequent step of a first embodiment of a semiconductor device fabrication method;

FIG. 7B shows a cross-sectional view along a y-axis of a semiconductor substrate illustrating a subsequent step of a first embodiment of a semiconductor device fabrication method;

FIG. 8A shows a cross-sectional view along an x-axis of a semiconductor substrate illustrating a subsequent step of a first embodiment of a semiconductor device fabrication method;

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FIG. 8B shows a cross-sectional view along a y-axis of a semiconductor substrate illustrating a subsequent step of a first embodiment of a semiconductor device fabrication method;

FIG. 9A shows a cross-sectional view along an x-axis of a semiconductor substrate illustrating a subsequent step of a first embodiment of a semiconductor device fabrication method;

FIG. 9B shows a cross-sectional view along a y-axis of a semiconductor substrate illustrating a subsequent step of a first embodiment of a semiconductor device fabrication method; and --

Please replace the paragraph beginning at page 4, line 25, with the following paragraphs:

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-- FIG. 10 shows a plan view of a semiconductor substrate illustrating a step of a second embodiment of a semiconductor device fabrication method;

FIG. 11 shows a cross-sectional view along a y-axis of a semiconductor substrate illustrating a subsequent step of a second embodiment of a semiconductor device fabrication method;

FIG. 12 shows a plan view of a semiconductor substrate illustrating a subsequent step of a second embodiment of a semiconductor device fabrication method;

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FIG. 13 shows a cross-sectional view along a y-axis of a semiconductor substrate illustrating a subsequent step of a second embodiment of a semiconductor device fabrication method;

FIG. 14 shows a plan view of a semiconductor substrate illustrating a subsequent step of a second embodiment of a semiconductor device fabrication method;

FIG. 15 shows a cross-sectional view along a y-axis of a semiconductor substrate illustrating a subsequent step of a second embodiment of a semiconductor device fabrication method;

FIG. 16 shows a cross-sectional view along a y-axis of a semiconductor substrate illustrating a subsequent step of a second embodiment of a semiconductor device fabrication method. --